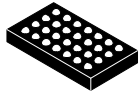


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

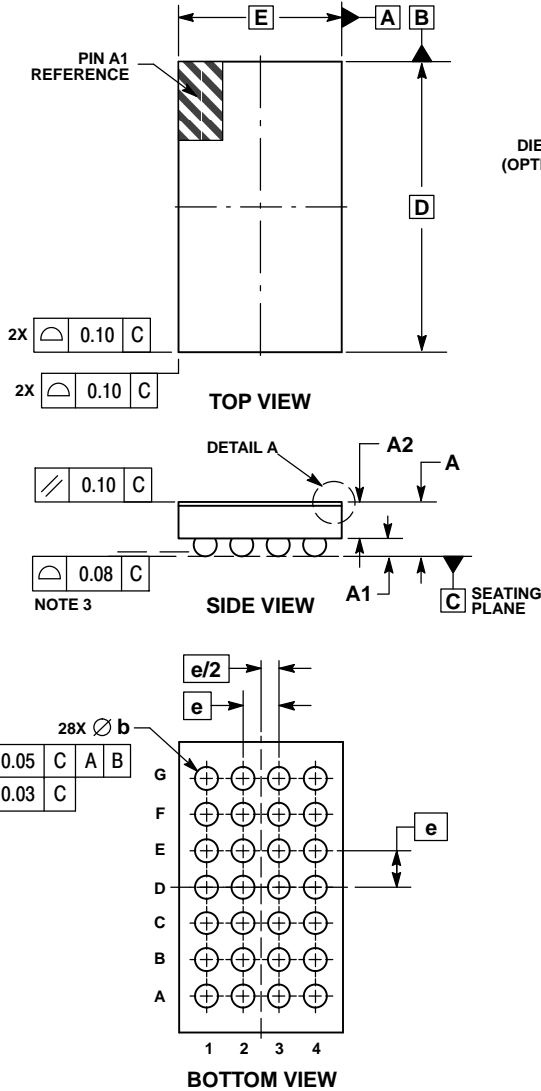
ON Semiconductor®



SCALE 4:1

WLCSP28, 2.9x1.9, 0.4P
CASE 567JJ
ISSUE D

DATE 18 NOV 2014

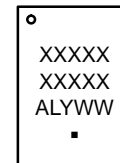


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.60
A1	0.17	0.23
A2	0.36 REF	
A3	0.02	0.03
b	0.24	0.30
D	2.90 BSC	
E	1.90 BSC	
e	0.40 BSC	

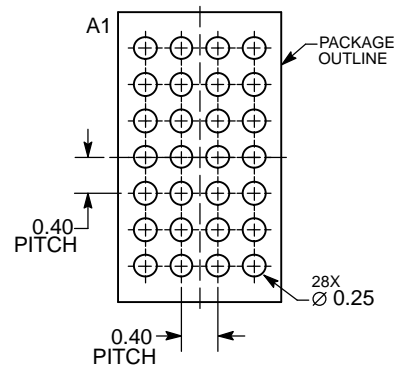
GENERIC MARKING DIAGRAM*



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WLCSP28, 2.9X1.9, 0.4P	PAGE 1 OF 2



ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY J. SAMUDIO.	12 NOV 2013
A	CHANGED PACKAGE DIMENSIONS FROM 3.2X1.8 TO 2.9X1.9. REQ. BY J. SAMUDIO.	09 DEC 2013
B	CHANGED DIMENSION b MAX VALUE FROM 0.28 TO 0.30MM. REQ. BY J. SAMUDIO.	13 JAN 2014
C	CHANGED DIMENSION A3 TO 0.04 REF. REQ. BY R. AVILA.	29 MAY 2014
D	CHANGED DIMENSION A3 FROM 0.04 REF BACK TO 0.02 MIN AND 0.03 MAX. REQ. BY J. SAMUDIO.	18 NOV 2014

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